

2872

APR 08 2002

**TRANSMITTAL LETTER**  
**(General - Patent Pending)**

Docket No.  
EN9-99-080

In Re Application Of: Caletka et al.

Serial No.  
09/438,037

Filing Date  
11/10/99

Examiner  
Mitchell, J.

Group Art Unit  
2827

Title: **PARTIALLY CAPTURED ORIENTED INTERCONNECTIONS FOR BGA PACKAGES  
AND A METHOD OF FORMING THE INTERCONNECTIONS**

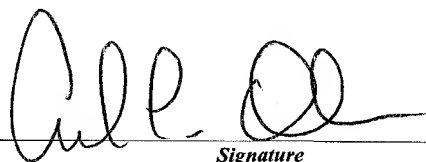
TO THE ASSISTANT COMMISSIONER FOR PATENTS:

Transmitted herewith is:

Amendment (9 pages)

in the above identified application.

- ☒ No additional fee is required.
- ☐ A check in the amount of \_\_\_\_\_ is attached.
- ☒ The Assistant Commissioner is hereby authorized to charge and credit Deposit Account No. **09-0457 (IBM)** as described below. A duplicate copy of this sheet is enclosed.
- ☐ Charge the amount of \_\_\_\_\_
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Signature

Dated: 4/2/2002

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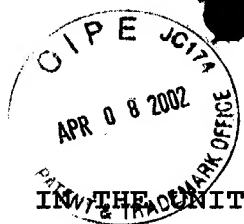
I certify that this document and fee is being deposited on 4/2/2002 with the U.S. Postal Service as first class mail under 37 C.F.R. 1.8 and is addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231.

  
Signature of Person Mailing Correspondence

Lisa A. Molloy

Typed or Printed Name of Person Mailing Correspondence

CC:



Docket No.: EN9-99-080

#9/a  
4/12/02  
Hawkins

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Caletka, et al. ) Examiner: Mitchell, J.  
Serial No.: 09/438,037 ) Art Unit: 2827  
Filing Date: 11/10/99 )  
Title: PARTIALLY CAPTURED ORIENTED INTERCONNECTIONS FOR BGA  
PACKAGES AND A METHOD OF FORMING THE INTERCONNECTIONS

Commissioner for Patents  
Washington D.C. 20231

AMENDMENT

Sir:

In response to the Office Action mailed February 26, 2002,  
please amend the above-identified patent application as follows:

IN THE CLAIMS:

Please amend the claims as follows:

14. (Amended) An integrated chip package comprising:

a first substrate and a second substrate, wherein the first  
and second substrates include a plurality of partially captured  
pads; and

a plurality of interconnections between the first and second  
substrates.

Serial No.: 09/438,037

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